

**AMENDMENTS TO THE CLAIMS**

Please **AMEND** claims 1 and 7 as shown below.

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently amended) A plasma display panel, comprising:  
a first substrate and a second substrate opposing one another with a predetermined gap therebetween; and  
a sealant formed on opposing surfaces of the first substrate and the second substrate ~~substrates~~ around an outer circumferential area of the first substrate and the second substrate to seal the first substrate and the second substrate,  
wherein the sealant is formed of regions having a first width of substantially the same size and regions having a second width, wherein the second width is greater than the first width, the sealant having a substantially uniform thickness.

2. (Original) The plasma display panel of claim 1, wherein the regions of the sealant having the second width are located at areas where a sealing pressure is concentrated.

3. (Original) The plasma display panel of claim 1, wherein a plurality of the regions of the sealant having the second width are formed at predetermined intervals around the circumferential areas of the first substrate and the second substrate.

4. (Original) The plasma display panel of claim 1, wherein when moving in one direction along a long axis of the sealant, regions of the sealant having the second width gradually increase in size from regions of the sealant having the first width until reaching the size of the second width, then the width of the sealant gradually decreases in size until it reaches the size of the first width.

5. (Original) The plasma display panel of claim 1, wherein the sealant is frit.

6. (Original) The plasma display panel of claim 1, wherein the regions of the sealant having the second width correspond to areas where sealant clips are mounted to the first substrate and the second substrate during a sealing process.

7. (Currently amended) A plasma display panel, comprising:  
a first substrate and a second substrate opposing one another with a predetermined gap therebetween; and  
a sealant formed on opposing surfaces of the first substrate and the second substrate around outer circumferential areas of the first substrate and the second substrate to seal the first substrate and the second substrate, the sealant formed having a substantially uniform thickness.

wherein a cross-section of the sealant is band-shaped with a plurality of nodes.

8. (Original) The plasma display panel of claim 7, wherein the nodes are formed at predetermined intervals around the circumferential areas of the first substrate and the second substrate.

9. (Original) The plasma display panel of claim 7, wherein the sealant is frit.
10. (Withdrawn) A method for sealing a first substrate of a plasma display panel with a second substrate of the plasma display panel, comprising:  
depositing a sealant along an outside border of the first substrate, wherein the sealant is deposited on a surface of the first substrate which opposes the second substrate and the sealant has a first width, which is substantially uniform, in a plurality of first areas and the sealant has a second width in second areas.
11. (Withdrawn) The method of claim 10, wherein the second width is larger than the first width.
12. (Withdrawn) The method of claim 10, wherein the second areas correspond to areas where sealant clips are used to apply pressure to seal the first substrate and the second substrate together.
13. (Withdrawn) The method of claim 10, wherein the sealant with the second width is obtained by increasing an injection speed of a dispenser which is dispensing the sealant.
14. (Withdrawn) The method of claim 10, wherein the sealant with the second width is obtained by controlling an amount of paste injection.
15. (Withdrawn) The method of claim 10, wherein the first areas of the sealant have variations in thickness of about 5 $\mu$ m or less.

16. (Withdrawn) The method of claim 10, wherein the second areas of the sealant have variations in thickness of about 5 $\mu$ m or less.

17. (Withdrawn) The method of claim 10, further comprising placing the second substrate on top of the first substrate.

18. (Withdrawn) The method of claim 17, further comprising:  
applying sealant clips to areas of the first substrate and the second substrate which correspond to the second areas,

wherein a thickness of the sealant in the second areas is substantially equal to a thickness of the sealant in the first areas, the thickness of the sealant being a length of the sealant along a plane perpendicular to the first substrate and the second substrate.

19. (Withdrawn) The method of claim 18, further comprising subjecting the first substrate and the second substrate to a temperature that is equal to or greater than a melting point of the sealant.

20. (Withdrawn) The method of claim 10, wherein the first width and the second width correspond to a length of the sealant along a plane which is parallel to the first substrate and the second substrate.